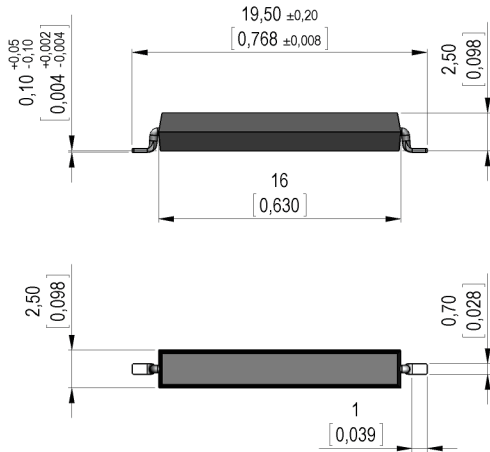


Dimensions mm[inch]
tolerances according to DIN ISO 2768-m
Toleranzen gem. DIN ISO 2768-m



Isometric
Scale:2:1
Maßstab 2:1

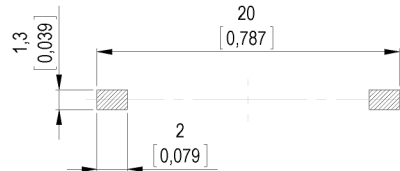


Marking

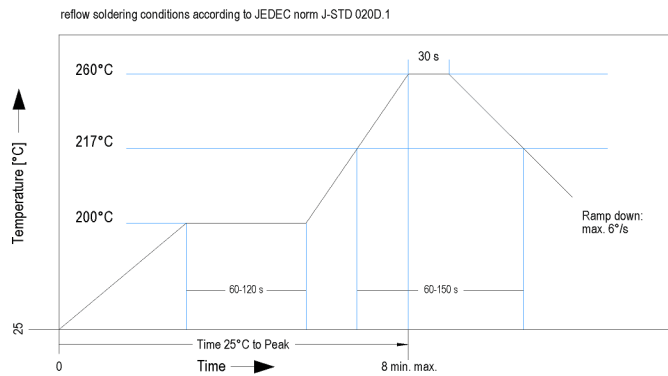
according to EN60062/factory code
gem. EN60062/Fertigungsstätte



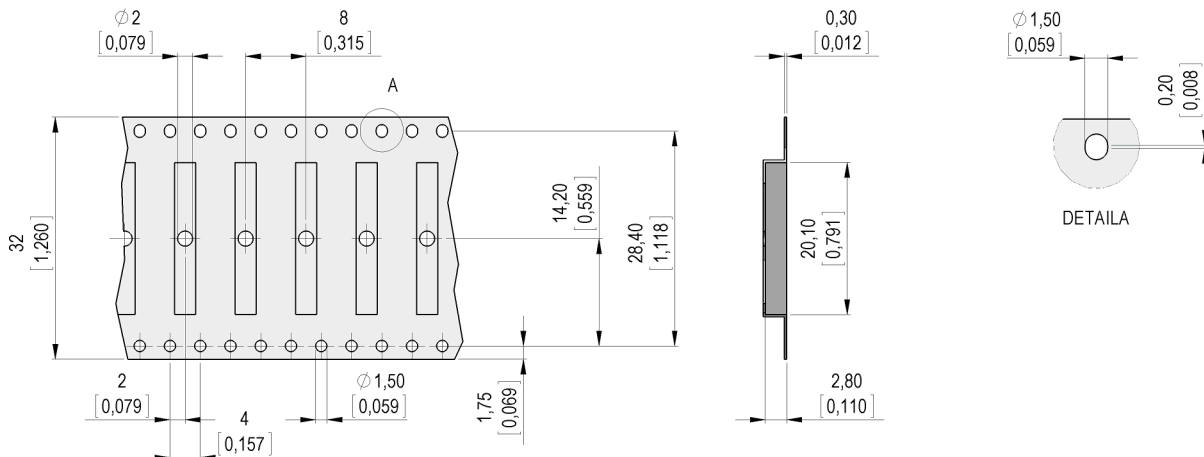
Recommended PCB Pad Layout



Solder Reflow Profile



Packaging





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 USA: +1 / 508 295 0771 | Email: salesusa@meder.com
 Asia: +852 / 2955 1682 | Email: salesasia@meder.com

Item No.:
9151710022
 Item:
MK15-B-2

| Magnetic properties | Conditions | Min | Typ | Max | Unit |
|---------------------------------------|---|-----|--------|-----|------|
| Pull-In | at 20°C | 18 | | 38 | |
| Test equipment | | | KMS-11 | | |
| Pull-In in milliTesla (modified conta | MS150 - phys. caused tolerance +/- 0,1mT | 1,2 | | 2,1 | mT |
| Test equipment | | | MS-150 | | |

| Contact data 66/1 | Conditions | Min | Typ | Max | Unit |
|----------------------------|--|-----|---------|------|------|
| Contact-material | | | Rhodium | | |
| Contact rating | Any DC combination of V & A not to exceed their individual max.'s | | | 10 | W |
| Switching voltage | DC or Peak AC | | | 180 | VDC |
| Switching current | DC or Peak AC | | | 0,5 | A |
| Carry current | DC or Peak AC | | | 1,25 | A |
| Contact resistance static | Measured with 40% overdrive Start Value | | | 150 | mOhm |
| Breakdown voltage (>20 AT) | according to IEC 255-5 | 200 | | | VDC |

| Special Product Data | Conditions | Min | Typ | Max | Unit |
|----------------------|------------|-----|----------------------|-----|------|
| Housing material | | | epoxy resin | | |
| Approval | | | UL- File-Nr. E156887 | | |

| Environmental data | Conditions | Min | Typ | Max | Unit |
|-----------------------------|-----------------------------------|-----|--------------|-----|------|
| Shock | 1/2 sine wave duration 11ms | | | 30 | g |
| Vibration | from 10 - 2000 Hz | | | 20 | g |
| Ambient temperature | | -40 | | 130 | °C |
| Storage temperature | | -50 | | 130 | °C |
| Soldering Temperature Tsold | Reflow acc.IPC/JEDEC J-STD-020D.1 | | | 260 | °C |
| Cleaning | | | fully sealed | | |

Modifications in the sense of technical progress are reserved

Designed at: 21.11.07 Designed by: THAUKE
 Last Change at: 12.12.13 Last Change by: THAUKE

Approval at: 23.11.07 Approval by:
 Approval at: 16.12.13 Approval by:

AWEBER

Version: 17